

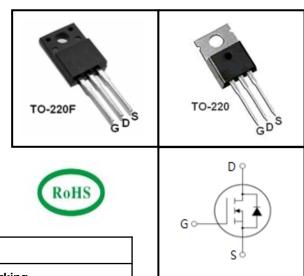
650V N-Channel MOSFET

FEATURES

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)



Device Marking and Package Information				
Device	Package	Marking		
TMA12N65H	TO-220F	A12N65H		
TMP12N65H	TO-220	P12N65H		

Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted					
Parameter	Symbol	Value		l locit	
Parameter		TO-220F	TO-220	Unit	
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	650		V	
Continuous Drain Current	I _D	12		А	
Pulsed Drain Current (note1)	I _{DM}	48		А	
Gate-Source Voltage	V _{GSS}	±30		V	
Single Pulse Avalanche Energy (note2)	E _{AS}	810		mJ	
Avalanche Current (note1)	I _{AR}	9		А	
Repetitive Avalanche Energy (note1)	E _{AR}	54		mJ	
Power Dissipation ($T_C = 25^{\circ}C$)	P _D	70	223	W	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150		°C	

Thermal Resistance				
Parameter	Compleal	Value		Unit
Farameter	Symbol	TO-220F	TO-220	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	1.78	0.56	•c/w
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	60	°C/VV



			Value				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	650			V	
Zoro Coto Voltago Droin Current		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 520V, V_{GS} = 0V, T_{J} = 125^{\circ}C$			50		
Gate-Source Leakage	$I_{\rm GSS}$	$V_{GS} = \pm 30V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3		4	٧	
Drain-Source On-Resistance (Note3)	R _{DS(on)}	V _{GS} = 10V, I _D = 6A		0.55	0.65	Ω	
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0V$,		1540		pF	
Output Capacitance	C _{oss}	$V_{DS} = 25V$,		175			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		21			
Total Gate Charge	Q_g			44		nC	
Gate-Source Charge	Q_{gs}	$V_{DD} = 520V, I_{D} = 12A,$ $V_{GS} = 10V$		8.6			
Gate-Drain Charge	Q_{gd}	30		21			
Turn-on Delay Time	$t_{d(on)}$			30			
Turn-on Rise Time	t _r	$V_{DD} = 325V, I_{D} = 12A,$		12			
Turn-off Delay Time	$t_{d(off)}$	$V_{DD} = 325V, I_D = 12A,$ $R_G = 25\Omega$		95		ns -	
Turn-off Fall Time	t _f			22			
Drain-Source Body Diode Characteris	stics						
Continuous Body Diode Current	Is	T 250C			12	۸	
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			48	Α	
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 12A$, $V_{GS} = 0V$			1.4	٧	
Reverse Recovery Time	t _{rr}	$V_{GS} = 0V, I_{F} = 12A,$		380		ns	
Reverse Recovery Charge	Q _{rr}	di _F /dt = 100A/μs		4.5		μC	

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 9A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 1\%$



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^{\circ}C$)

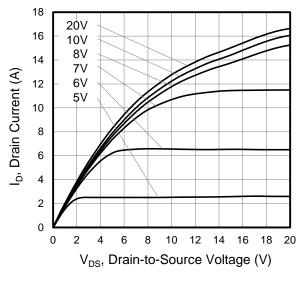


Figure 2. On-Resistance vs. Drain Current

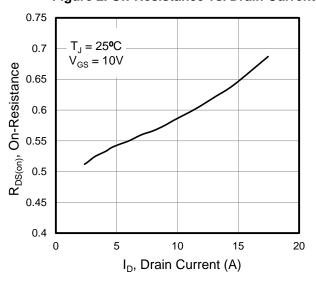


Figure 3. BV_{DSS} vs. Temperature

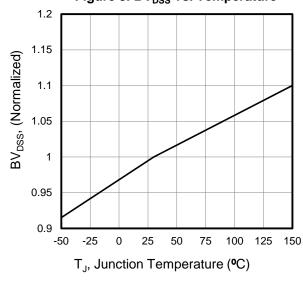
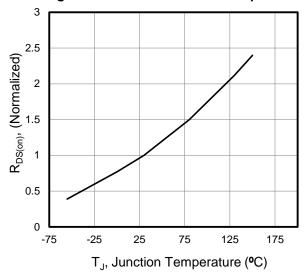


Figure 4. On-Resistance vs. Temperature



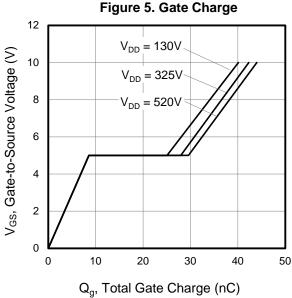
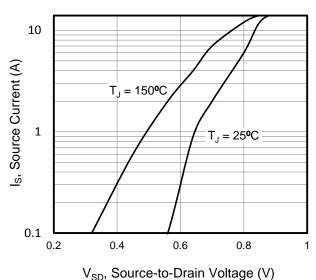


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. Transient Thermal Impedance

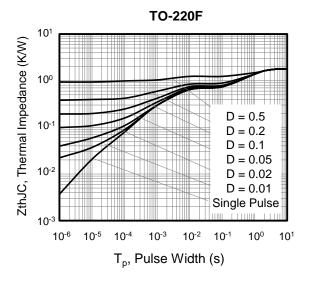


Figure 8. Transient Thermal Impedance

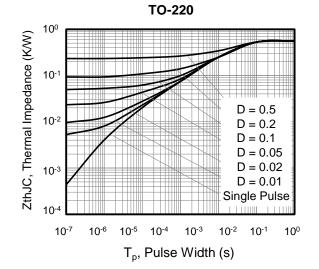




Figure A: Gate Charge Test Circuit and Waveform

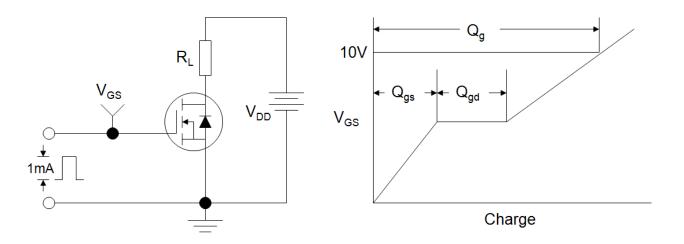


Figure B: Resistive Switching Test Circuit and Waveform

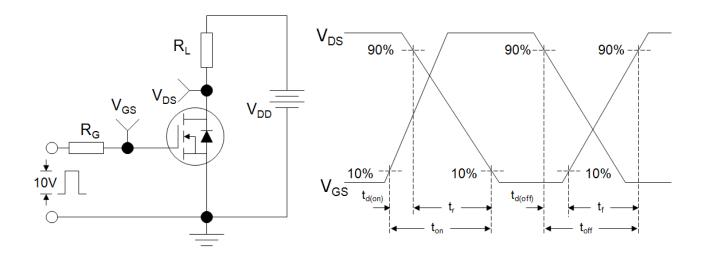
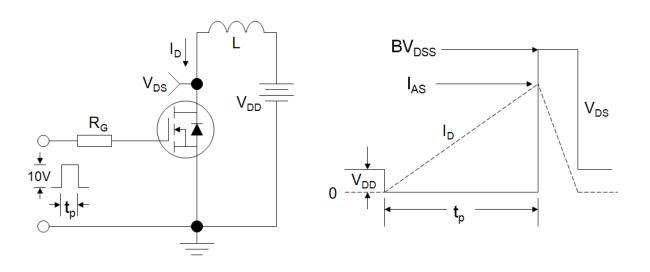
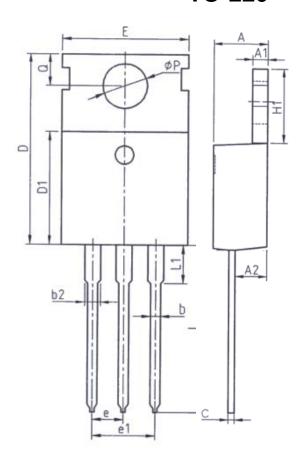


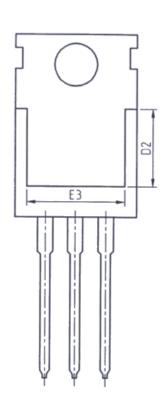
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220



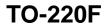


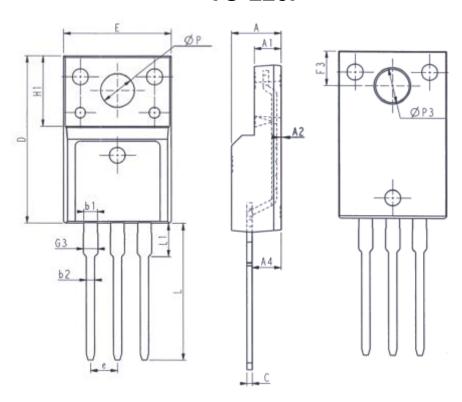
Unit: mm					
Symbol	Min.	Max.			
Α	4. 37	4. 77			
A1	1. 25	1. 45			
A2	2. 20	2. 60			
ь	0. 70	0. 95			
b2	1. 17	1. 47			
С	0. 40	0. 65			
D	15. 10	16. 10			
D1	8. 80	9. 40			
D2	5. 50	_			

Unit: mm				
Symbol	Min.	Max.		
E	9. 70	10. 30		
E3	7. 00 -			
е	2. 54BSC			
e1	5. 08BSC			
H1	6. 25	6. 85		
L	12. 75	13. 80		
L1	-	3. 40		
P	3. 40	3. 80		
Q	2. 60 3. 00			









Unit: mm		Unit: mm			
Symbol	Min.	Max.	Symbol	Symbol Min.	
E	9. 96	10. 36	L	12. 68	13. 28
Α	4. 50	4. 90	L1	2. 93	3. 13
A 1	2. 34	2. 74	Р	3. 03	3. 38
A2	0. 30	0.60	Р3	3. 15	3. 65
A4	2. 56	2. 96	F3	3. 15	3. 45
С	0.40	0. 65	G3	1. 25	1. 55
D	15. 57	16. 17	b1	1. 18	1. 43
H1	6. 70REF		b2	0. 70	0. 95
e	2. 54BSC				



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